

60V N+N-Channel Enhancement Mode MOSFET

Description

The HN50H06S uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = 60V$ $I_D = 50A$

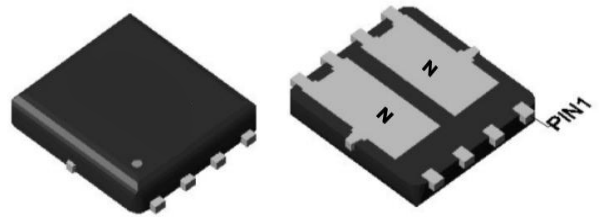
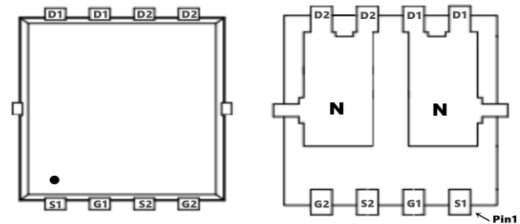
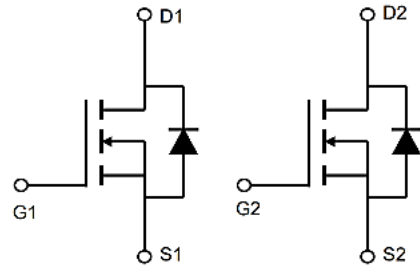
$R_{DS(ON)} < 16m\Omega$ @ $V_{GS}=10V$ (Type: 11m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HN50H06NF	PDFN5*6-8L	HN50H06NF XXX YYYY	5000

Absolute Maximum Ratings ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	50	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	25	A
IDM	Pulsed Drain Current ²	150	A
EAS	Single Pulse Avalanche Energy ³	64	mJ
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation ⁴	3.6	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.8	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	25	$^\circ\text{C/W}$

60V N+N-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	60	65	---	V
$\Delta BVDSS/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1mA$	---	0.057	---	$V/^{\circ}\text{C}$
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=12A$	---	11	16	m Ω
		$V_{GS}=4.5V, I_D=10A$	---	15	20	
VGS(th)	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.68	---	mV/ $^{\circ}\text{C}$
IDSS	Drain-Source Leakage Current	$V_{DS}=48V, V_{GS}=0V, T_J=25^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=48V, V_{GS}=0V, T_J=55^{\circ}\text{C}$	---	---	5	
IGSS	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=15A$	---	45	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.7	---	Ω
Q_g	Total Gate Charge (4.5V)	$V_{DS}=48V, V_{GS}=4.5V, I_D=15A$	---	19.3	---	nC
Q_{gs}	Gate-Source Charge		---	7.1	---	
Q_{gd}	Gate-Drain Charge		---	7.6	---	
Td(on)	Turn-On Delay Time	$V_{DD}=30V, V_{GS}=10V, R_G=3.3\Omega, I_D=15A$	---	7.2	---	ns
T_r	Rise Time		---	50	---	
Td(off)	Turn-Off Delay Time		---	36.4	---	
T_f	Fall Time		---	7.6	---	
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	2423	---	pF
Coss	Output Capacitance		---	145	---	
Crss	Reverse Transfer Capacitance		---	97	---	
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	35	A
ISM	Pulsed Source Current ^{2,5}		---	---	80	A
VSD	Diode Forward Voltage ²	$V_{GS}=0V, I_S=A, T_J=25^{\circ}\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$IF=15A, di/dt=100A/\mu s, T_J=25^{\circ}\text{C}$	---	16.3	---	nS
Q_{rr}	Reverse Recovery Charge		---	11	---	nC

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3、The power dissipation is limited by 150°C junction temperature
- 4、The EAS data shows Max. rating . The test condition is $V_{DD}=48V, V_{GS}=10V, L=0.1mH, I_{AS}=25A$, starting $T_J=25^{\circ}\text{C}$
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

60V N+N-Channel Enhancement Mode MOSFET

Typical Characteristics

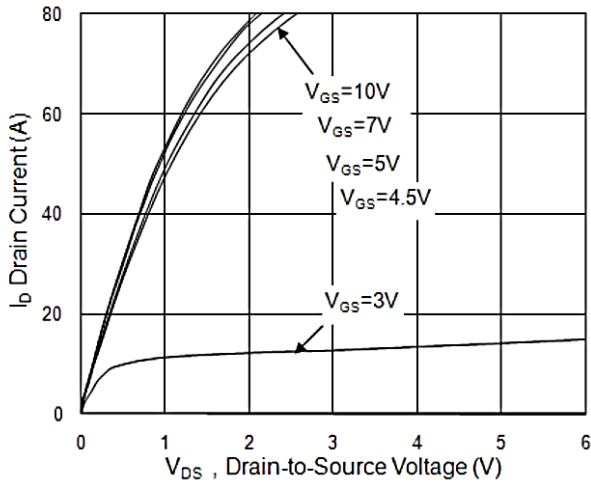


Fig.1 Typical Output Characteristics

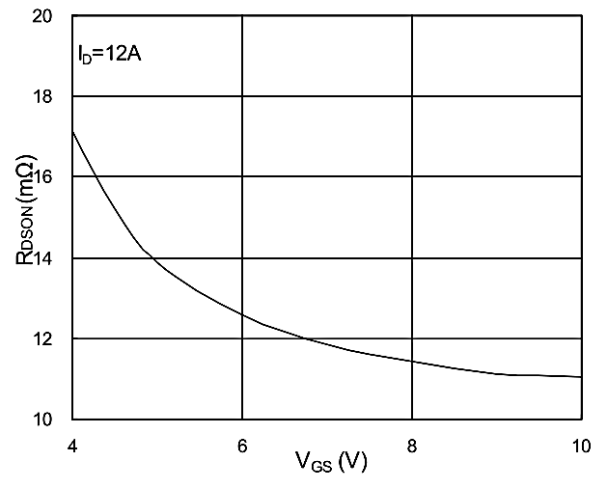


Fig.2 On-Resistance v.s Gate-Source

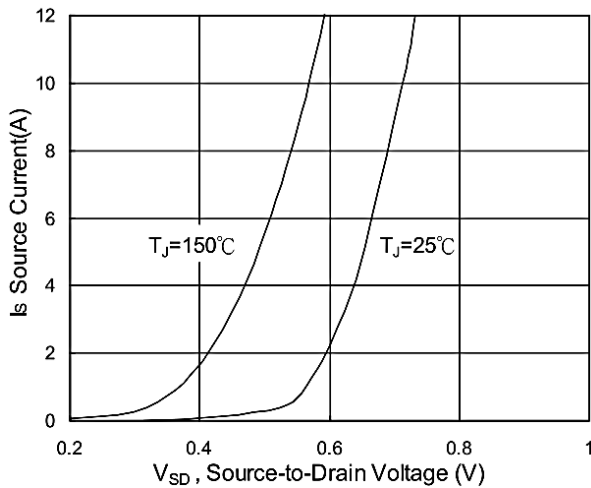


Fig.3 Forward Characteristics of Reverse

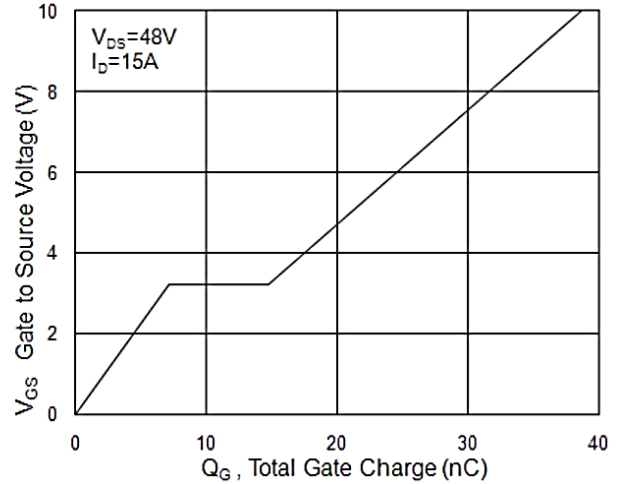


Fig.4 Gate-Charge Characteristics

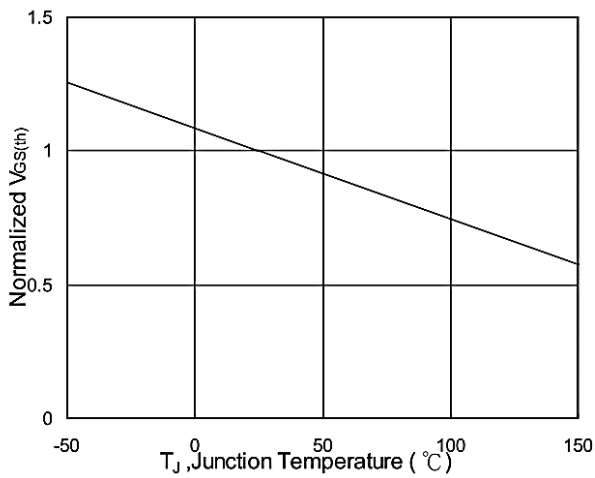


Fig.5 Normalized V_{GS} v.s T_J

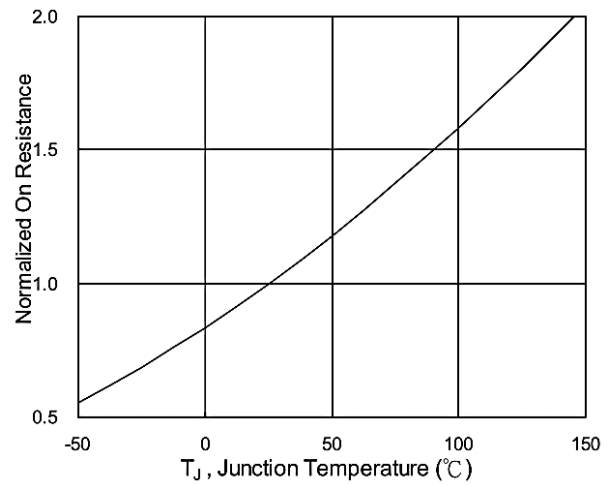


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

60V N+N-Channel Enhancement Mode MOSFET

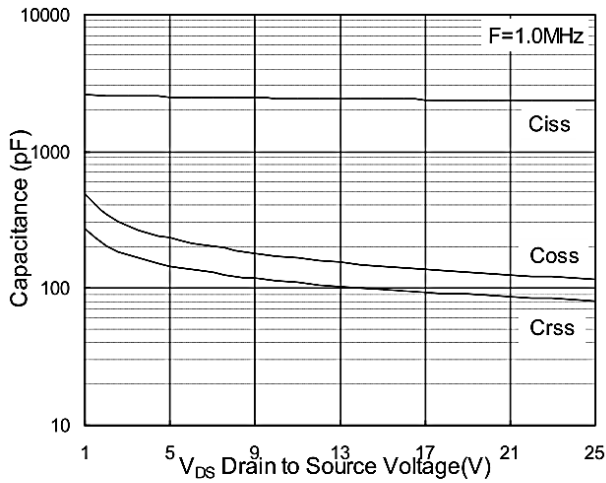


Fig.7 Capacitance

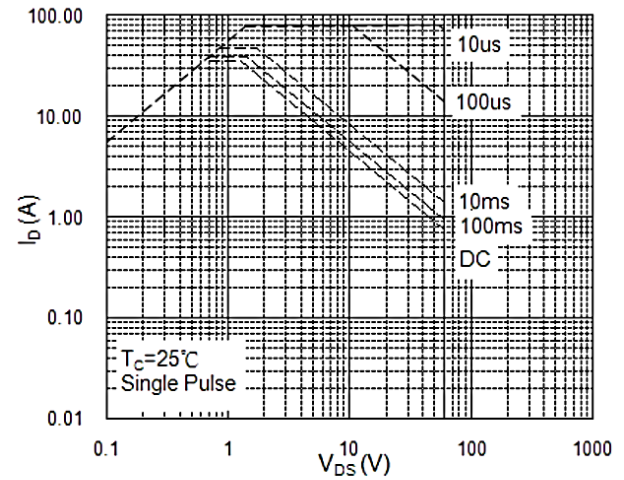


Fig.8 Safe Operating Area

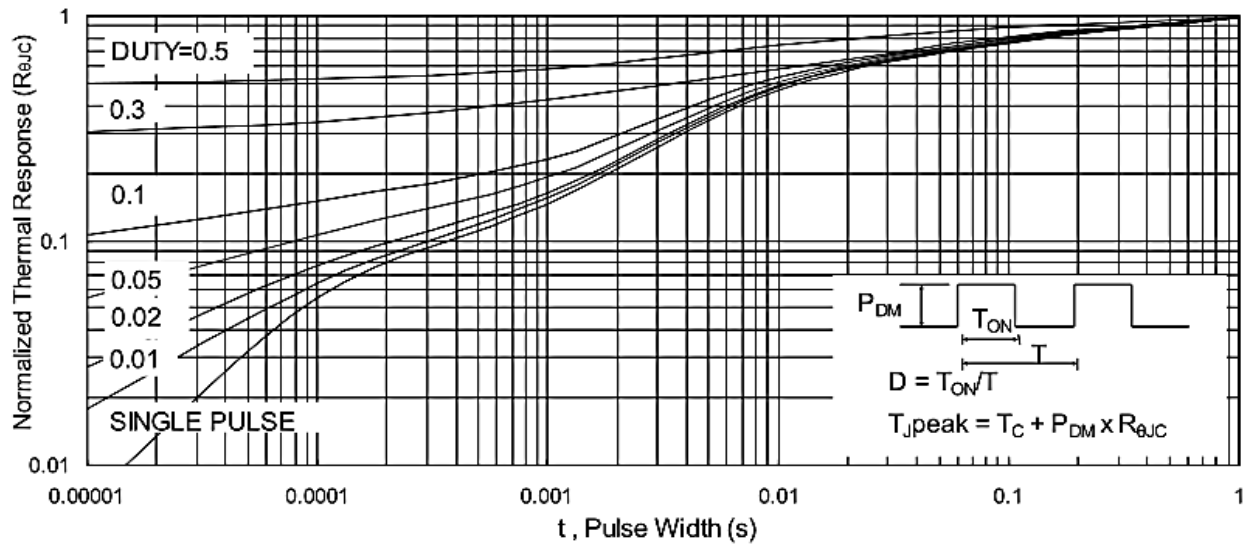


Fig.9 Normalized Maximum Transient Thermal Impedance

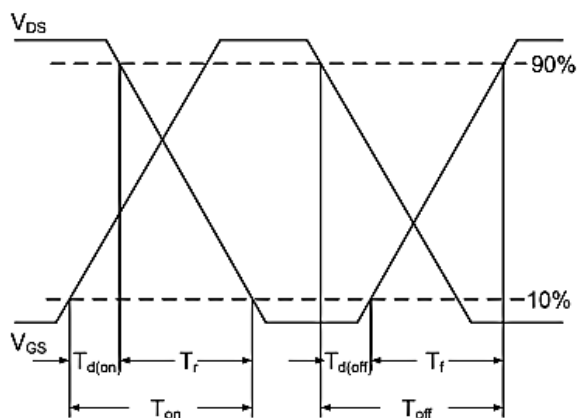


Fig.10 Switching Time Waveform

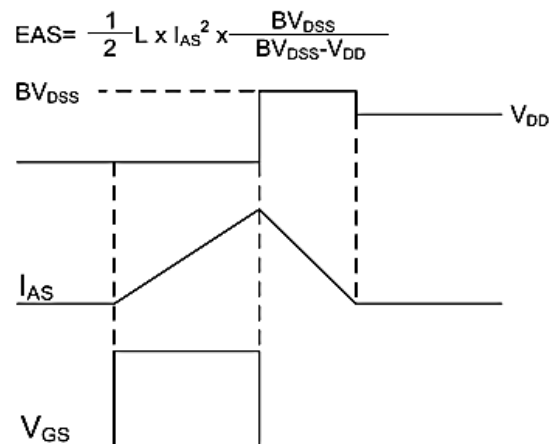
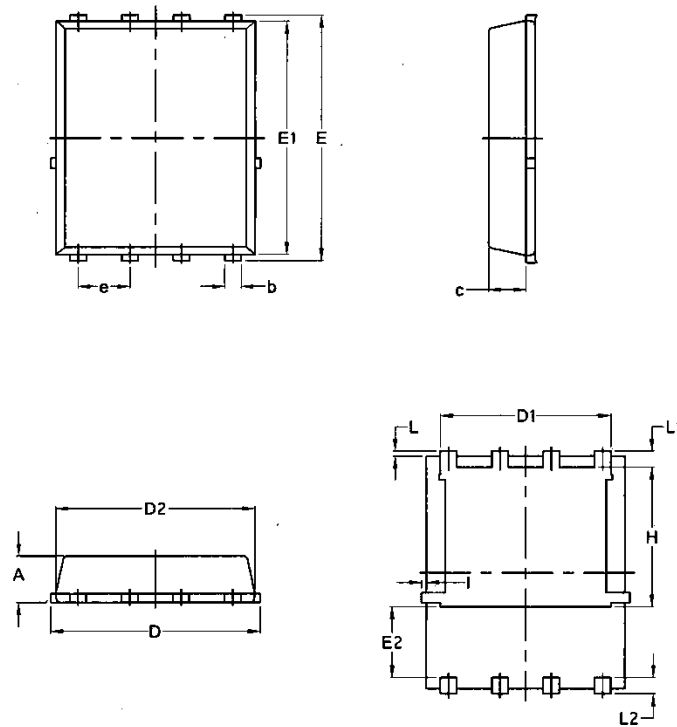


Fig.11 Unclamped Inductive Switching Waveform

60V N+N-Channel Enhancement Mode MOSFET

Package Mechanical Data-DFN5*6-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070